



Product Change Notification - KSRA-29YJZS457

Date:

01 Feb 2019

Product Category:

Crypto Memory

Affected CPNs:**Notification subject:**

CCB 3701 Initial Notice: Qualification of new module tape for selected Atmel Smart Card Modules available in SCC package at AIC assembly site.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of new module tape for selected Atmel Smart Card Modules available in SCC package at AIC assembly site.

Pre Change:

Using 9X16002FA lead frame material and module tape with cavity and without re-inforced sprocket holes

Post Change:

Using 9X16004AAU lead frame material and module tape without cavity and with re-inforced sprocket holes

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	AIC Semiconductor Sdn Bhd / AIC	AIC Semiconductor Sdn Bhd / AIC
Wire material	Au	Au
Die attach material	Ablestik 2035SC	Ablestik 2035SC
Glob Top	Vitralit 1650	Vitralit 1650
Lead frame material	9X16002FA	9X16004AAU
	with cavity	without cavity
Module Tape	without re-inforced sprocket holes	with re-inforced sprocket holes
	(see attached photos for reference)	(see attached photos for reference)

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by implementing new module tape for smart card modules

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

May 2019



Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts

Time Table Summary:

	February 2019					📅	May 2019				
Workweek	05	06	07	08	09	📅 📅 📅	18	19	20	21	22
Initial PCN Issue Date	X										
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

February 01, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-29YJZS457_Pre and Post Change Summary.pdf](#)

[PCN_KSRA-29YJZS457_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

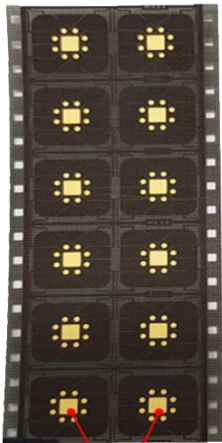

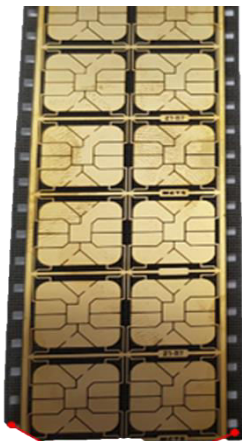

AT88AA001-MJ
AT88AA001-MJTG
AT88AK001-MJ
AT88SC0104CA-MJ
AT88SC0104CA-MJTG
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AT88SC0104C-ME
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AT88SC0104C-MP
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AT88SC102-09ET-19
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AT88SC12816C-MJTG
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AT88SC1608-09ET-00
AT88SC1608-09ET-10
AT88SC1608-09PT-01
AT88SC1608-09PT-07
AT88SC1616C-ME
AT88SC1616C-MJ
AT88SC1616C-MJTG
AT88SC1616C-MP
AT88SC1616C-MPTG
AT88SC25616C-MB
AT88SC25616C-MJ
AT88SC25616C-MJTG
AT88SC3216C-MJ
AT88SC3216C-MJTG
AT88SC6416C-MJ
AT88SC6416C-MJTG

Notification Subject:

CCB 3701 Initial Notice: Qualification of new module tape for selected Atmel Smart Card Modules available in SCC package at AIC assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	AIC Semiconductor Sdn Bhd / AIC	AIC Semiconductor Sdn Bhd / AIC
Wire material	Au	Au
Die attach material	Ablestik 2035SC	Ablestik 2035SC
Glob Top	Vitralit 1650	Vitralit 1650
Lead frame material	9X16002FA	9X16004AAU
Module Tape	with cavity  With cavity	without cavity  Non-cavity
	without re-inforced sprocket holes  Without Re-inforced sprocket holes	with re-inforced sprocket holes  Re-inforced sprocket holes



QUALIFICATION PLAN SUMMARY

PCN #: KSRA-29YJZS457

**Date:
January 24, 2019**

**Qualification of new module tape for selected Atmel Smart
Card Modules available in SCC package at AIC assembly
site.**

Purpose: Qualification of new module tape for selected Atmel Smart Card Modules available in SCC package at AIC assembly site.

CCB No.: 3701

MP code: 56815SH7BC08

CPN : AT88SC25616C-MJ

BD No: Atmel B/D: W568159XUJ, MCHP B/D : BDM-002058A

Misc.	Assembly site	AIC
	BD Number	BDM-002058A
	MP Code (MPC)	56815SH7BC08
	Part Number (CPN)	AT88SC25616C-MJ
Lead-Frame	Paddle size	No Cavity
	Material	8 pin Contact nxtl plating
	Part Number	9X16004AAU
	Lead Plating	AU
Bond Wire	Material	Gold wire
Die Attach	Part Number	Ablestik 2035SC
	Conductive	Non-Conductive
GlobTop	Part Number	Vitralit 1650
PKG	PKG Type	Smart Card M2
	Pin/Ball Count	8
	PKG width/size	12.6mm x 11.4mm x 0.58mm
Die	Die Thickness	7.0 mils +/- 0.5mils
	Die Size	2.170 X 2.970mm
	Fab Process (site)	MCSO 6"

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	AIC	AIC & MCSO	SCC	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5	AIC	AIC & MCSO	SCC	30 bonds from a min. 5 devices.
Physical Dimmensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	AIC	AIC & MCSO	SCC	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	AIC	AIC & MCSO	SCC	
Temp Cycle	-25°C to +80°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	AIC	AIC & MCSO	SCC	Spares should be properly identified. Lot to go thru standard production testing and then be sent to MCSO for TC testing.